Low Distortion Internally Matched Power GaAs FETs (C-Band)

Features

- · Low intermodulation distortion
 - $IM_3 = -43 \, dBc \, at \, Po = 34.5 \, dBm$
 - Single carrier level
- · High power
 - $P_{1dB} = 44.5 \text{ dBm}$ at 7.7 GHz to 8.5 GHz
- · High gain
 - $G_{1dB} = 6.0 dB$ at 7.7 GHz to 8.5 GHz
- · Broad band internally matched
- · Hermetically sealed package

RF Performance Specifications (Ta = 25° C)

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P _{1dB}		dBm	43.5	44.5	_
Power Gain at 1dB Compression Point	G _{1dB}	V _{DS} = 10V	dB	5.0	6.0	_
Drain Current	I _{DS1}	f = 7.7 ~ 8.5 GHz	Α	_	8.0	9.0
Gain Flatness	ΔG		dB	_	_	±0.8
Power Added Efficiency	η _{add}		%	_	26	_
3rd Order Intermodulation Distortion	IM ₃	Note 1	dBc	-40	-43	_
Drain Current	I _{DS2}	Note i	Α	-	8.0	9.0
Channel-Temperature Rise	ΔT_ch	V _{DS} xI _{DS} xR _{th} (c-c)	°C	-	_	80

Electrical Characteristics (Ta = 25° C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Trans-conductance	gm	$V_{DS} = 3V$ $I_{DS} = 10.5A$	mS	_	6300	_
Pinch-off Voltage	V_{GSoff}	$V_{DS} = 3V$ $I_{DS} = 140 \text{mA}$	V	-2	-3.5	-5.0
Saturated Drain Current	I _{DSS}	$V_{DS} = 3V$ $V_{GS} = 0V$	Α	_	20	26
Gate-Source Breakdown Voltage	$V_{\rm GSO}$	$I_{GS} = -420\mu A$	V	-5	-	-
Thermal Resistance	R _{th (c-c)}	Channel to case	°C/W	_	0.8	1.0

Note 1: 2 tone Test Pout = 34.5dBm Single Carrier Level.

The information contained here is subject to change without notice.

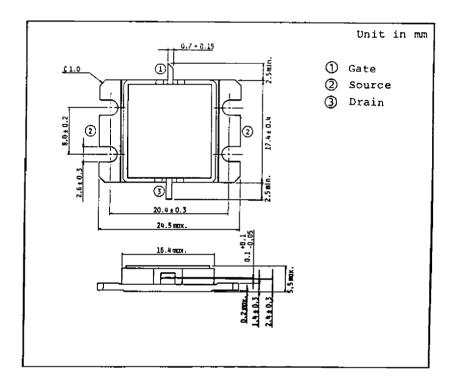
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Absolute Maximum Ratings (Ta = 25° C)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V_{DS}	V	15
Gate-Source Voltage	V_{GS}	V	-5
Drain Current	I _{DS}	Α	26
Total Power Dissipation (T _c = 25°C)	P_{T}	W	120
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65~175

Package Outline (2-16G1B)

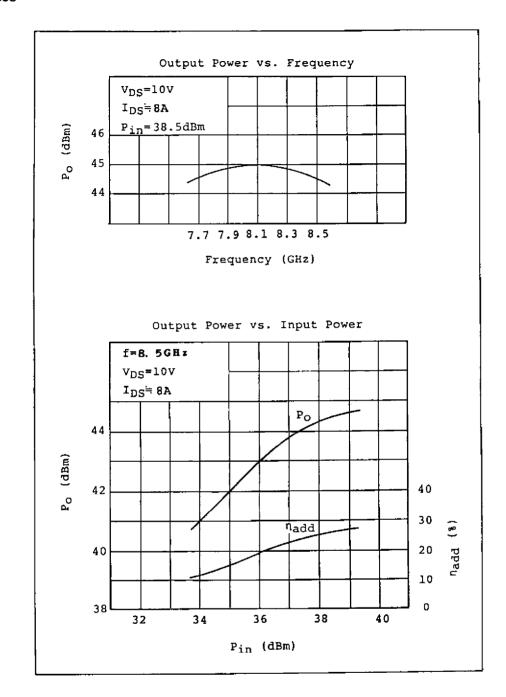


Handling Precautions for Packaged Type

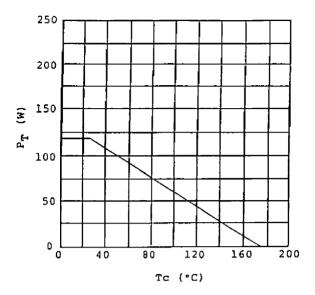
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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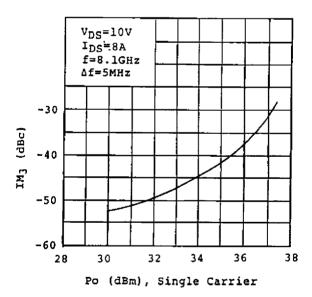
RF Performances



Power Dissipation vs. Case Temperature



IM₃ vs. Output Power Characteristics

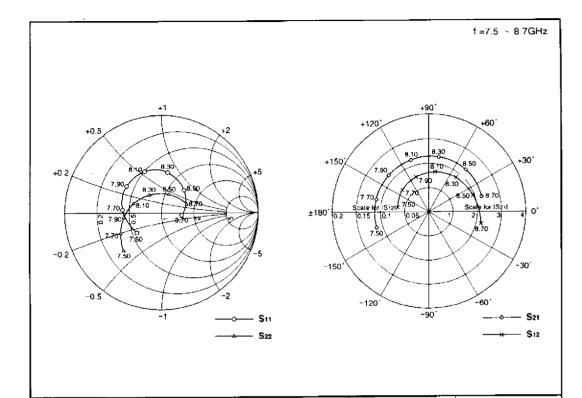


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TIM7785-30L S-Parameters (MAGN. and ANGLES)

 $V_{DS} = 10V$, $I_{DS} = 8.0A$



FREQUENCY	S11		S12		\$21		S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
7.50	0.326	-141.3	0.065	171.9	2.250	-163.3	0.553	-135.0
7.70	0.406	175.6	0.071	140.3	2.249	166.8	0.474	-153.7
7.90	0.457	142.4	0.076	110.4	2.242	138.0	0.391	-173.7
8.10	0.463	112.4	0.083	81.1	2.257	109.3	0.304	161.5
8.30	0.422	81.6	0.090	51.4	2.287	79.8	0.223	124.1
8.50	0.332	45.7	0.097	20.2	2.301	48.7	0.206	67.7
8.70	0.207	-6.0	0.101	-12.8	2.262	15.9	0.275	19.2
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